HC8LP

Low profile, high current power inductors

Applications

- Multi-phase regulators
- Voltage Regulator Modules (VRMs)
- Distributed power systems DC-DC converters
- Notebook and laptop regulators
- Desktop and server VRMs and EVRDs
- Point-of-Load (POL) modules
- Battery power systems
- High current power supplies
- Data networking and storage systems

Product description

- Low profile surface mount inductors designed for higher speed switch mode applications requiring low voltage, and high current
- Design utilizes high temperature powder iron material with a non-organic binder to eliminate thermal aging
- Inductance range from 0.17 uH to 47.9 uH
- Current range from 1.7 to 56 Amps
- Frequency range 1kHz to 500kHz

Environmental data

- Storage temperature range (component): -40°C to +155°C
- Operating temperature range: -40°C to +155°C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant

RoHS

Pb

Powering Business Worldwide

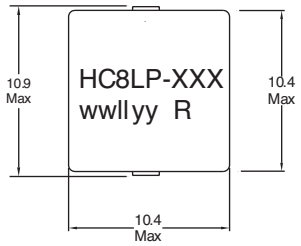
Product specifications

Part number[6]	OCL[1] (µH) ±20%	I_{rms}[2] (amps)	I_{sat}[3] (amps) 15% rolloff	I_{sat}[4] (amps) 30% rolloff	DCR (mΩ) maximum @ 20°C	Volt-µSec[5] (V-µs)
HC8LP-R15-R	0.170	29.0	31	56	1.40	7.8
HC8LP-R39-R	0.430	20.2	19	34	2.80	4.7
HC8LP-R75-R	0.830	15.6	13.5	24	4.70	3.4
HC8LP-1R2-R	1.35	12.4	10.1	18.7	7.50	2.6
HC8LP-1R9-R	1.92	10.1	8.7	15.5	11.5	4.1
HC8LP-2R6-R	2.67	8.3	7.4	13.1	17.1	4.8
HC8LP-3R5-R	3.56	6.9	6.4	11.4	24.5	5.6
HC8LP-4R5-R	4.57	6.5	5.6	10.0	27.6	6.3
HC8LP-5R6-R	5.71	5.5	5.1	9.0	38.9	7.1
HC8LP-6R9-R	6.98	5.2	4.6	8.1	42.8	7.8
HC8LP-8R2-R	8.37	4.5	4.2	7.4	58.0	8.6
HC8LP-100-R	9.90	4.3	6.8	3.8	62.9	9.3
HC8LP-150-R	15.2	3.4	3.1	5.5	99.4	11.6
HC8LP-220-R	21.7	2.8	2.6	4.6	149	13.7
HC8LP-330-R	32.1	2.3	2.1	3.8	224	16.8
HC8LP-470-R	47.9	1.8	1.7	3.1	344	20.3

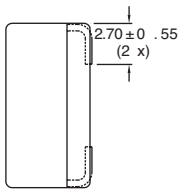
1. Open Circuit Inductance (OCL) Test Parameters: 100kHz, 1.0Vrms, 0.0Adc, @ +25°C
2. Irms: DC current for an approximate DT of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 155°C under worst case operating conditions verified in the end application.
3. Peak current for approximately 15% rolloff @+20°C
4. Peak current for approximately 30% rolloff @+20°C
5. Applied Volt-Time product (V-µs) across the inductor. This value represents the applied V-µs at operating frequency necessary to generate additional core loss which contributes to the 40°C temperature rise. De-rating of the I_{rms} is required to prevent excessive temperature rise. The 100% V-us rating is equivalent to a ripple current Ip-p of 20% of Isat (30% rolloff option).
6. Part number definition: HC8LP-XXX-R
   HC8LP = Product code and size
   XXX = Inductance value in uH. R = Decimal point. If no R is present then last character equals number of zeros
   -R suffix indicates RoHS compliant

Dimensions–mm

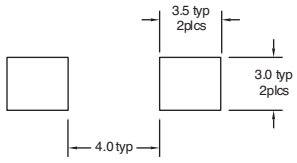
TOP VIEW



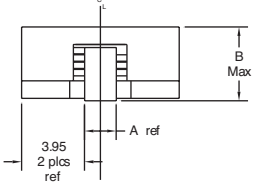
SIDE VIEW



RECOMMENDED PAD LAYOUT



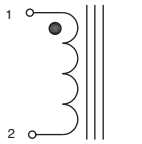
FRONT VIEW



FRONT VIEW
Dimesional Table

PN	A ref mm	B max mm
R15	2.1	3.5
R39	2.1	3.5
R75	2.1	3.5
1R2	2.1	3.3
1R9 thru 470	2.7	3.5

SCHEMATIC



Part marking: HC8LP= (Product code and size)-xxx=(inductance value in uH, R= decimal point. If no R is present then last character equals number of zeros. wwlyly=date code, R=revision level

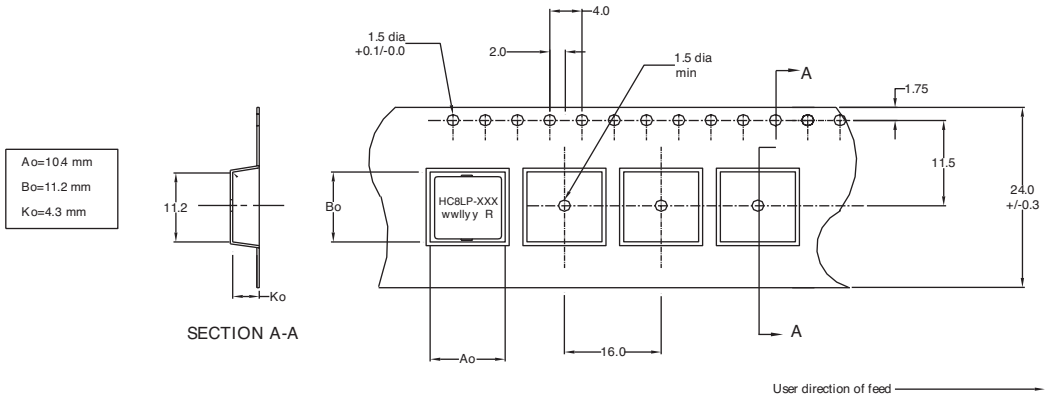
Tolerances are ±0.2 millimeters unless stated otherwise

All soldering surfaces to be coplanar within 0.1 millimeters

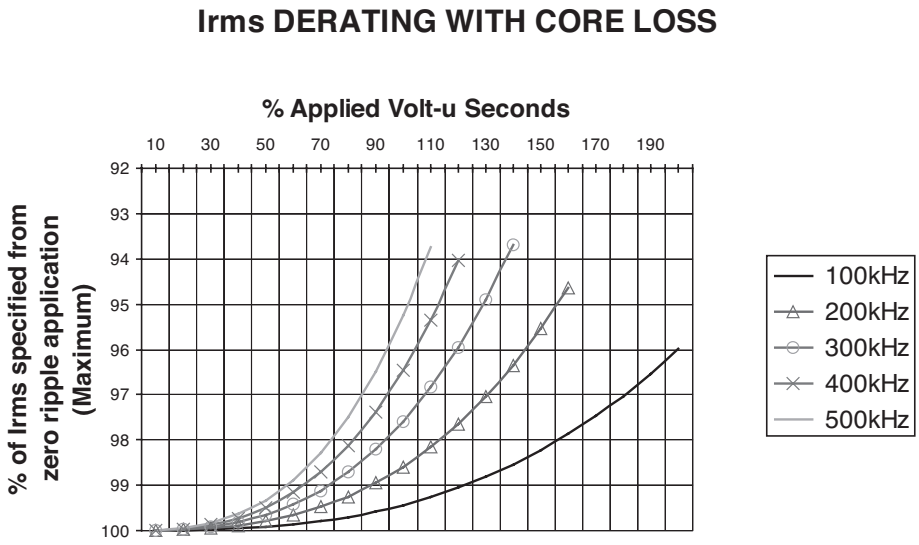
Do not route traces or vias underneath the inductor

Packaging information–mm

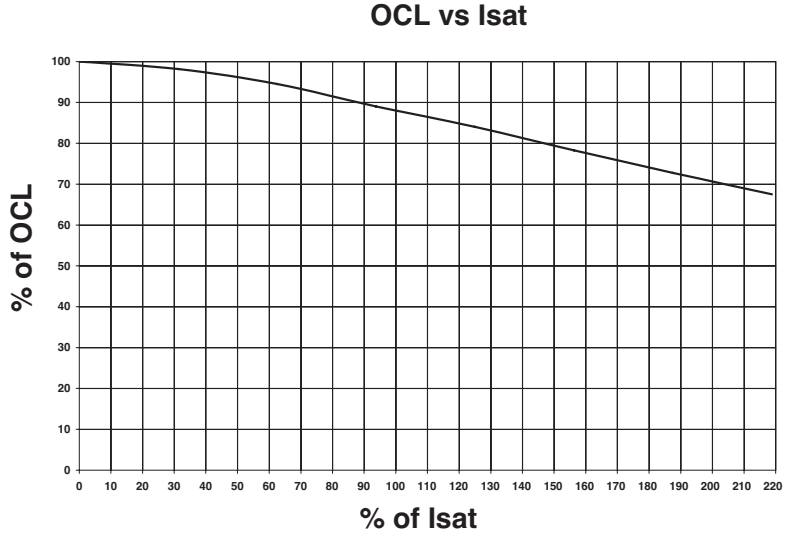
Supplied in tape and reel packaging, 800 parts per reel



Core loss



Rolloff



Solder reflow profile

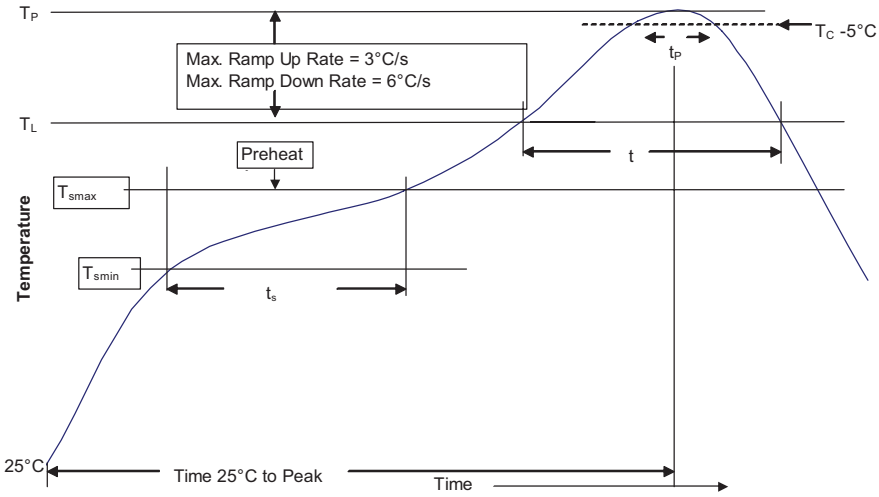


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T_{smin})	100°C	150°C
	• Temperature max. (T_{smax})	150°C	200°C
	• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p		3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L) Time at liquidous (t_L)		183°C 60-150 Seconds	217°C 60-150 Seconds
Peak package body temperature (T_P)*		Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)		20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})		6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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